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## Is Now



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# NLHV001

## 1-Bit Gate Pulse Modulator

The NLHV001 is a 1-bit gate pulse modulator designed to translate logic voltages for TFT LCD panels. This part translates a low voltage logic input signal to an output voltage of 15 V to 38 V. In addition, the NLV001 provides a user selectable delay and fall time on the high-to-low edge of the output signal. The delay and fall times are controlled by the magnitudes of the external capacitor resistor, respectively.

### Features

- Gate Pulse Modulation (GPM)
- TFT LCD Flicker Compensation Circuit
- Reduction of Coupling Effect Between Gate Line and Pixel
- Provides Power Sequencing Circuit for Gate Driver IC
- Wide Power Supply Operation: 15 V to 38 V
- Adjustable Output Delay and Fall Time
- This is a Pb-Free Device

### Typical Applications

- TFT LCDs

### Important Information

- ESD Protection for All Pins:  
Human Body Model (HBM) > 3000 V

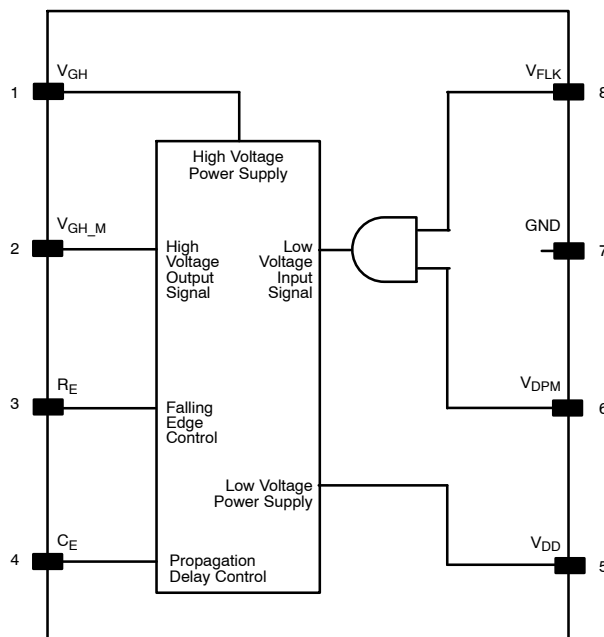
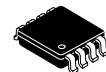


Figure 1. Block Diagram



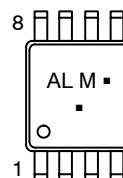
ON Semiconductor®

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US8  
US SUFFIX  
CASE 493

### MARKING DIAGRAM



AL = Device Code  
M = Date Code\*  
■ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

### ORDERING INFORMATION

See detailed ordering and shipping information on page 10 of this data sheet.

# PIN DESCRIPTION

Pin	Pin Name	Pin Function	Comment
1	V <sub>GH</sub>	Power Supply Input	V <sub>GH</sub> = 15 to 38 V
2	V <sub>GH_M</sub>	Output	This output directly drives the power supply of Gate Driver IC
3	R <sub>E</sub>	R <sub>E</sub> pin used to set the falling edge time (t <sub>fall</sub> )	The Delay time is programmed by connecting resistor R <sub>E</sub> to V <sub>GH</sub> and capacitor C <sub>E</sub> to ground.
4	C <sub>E</sub>	C <sub>E</sub> pin used to set the propagation delay time (t <sub>phl</sub> )	
5	V <sub>DD</sub>	Reference to input	The reference input pin is used to reduce flicker. The reference input voltage is as follows: V <sub>DD</sub> ≤ V <sub>GH</sub> - 8.5 V, V <sub>DD</sub> = 0 to 25 V
6	V <sub>DPM</sub>	Signal input 1	V <sub>DPM</sub> single input voltage is as follows: V <sub>DPM</sub> = 0 V to V <sub>GH</sub> . The V <sub>DPM</sub> pin is used to create a delay with the V <sub>GH</sub> to prevent system latch-up. V <sub>DPM</sub> also determines the time V <sub>GH</sub> is ON.
7	GND	Ground	
8	V <sub>FLK</sub>	Signal input 2	V <sub>FLK</sub> single input voltage is as follows: V <sub>DPM</sub> = 0 V to V <sub>GH</sub> . The V <sub>FLK</sub> determines the ON/OFF time of the TFT LCD and is produced from LCD timing controller module.

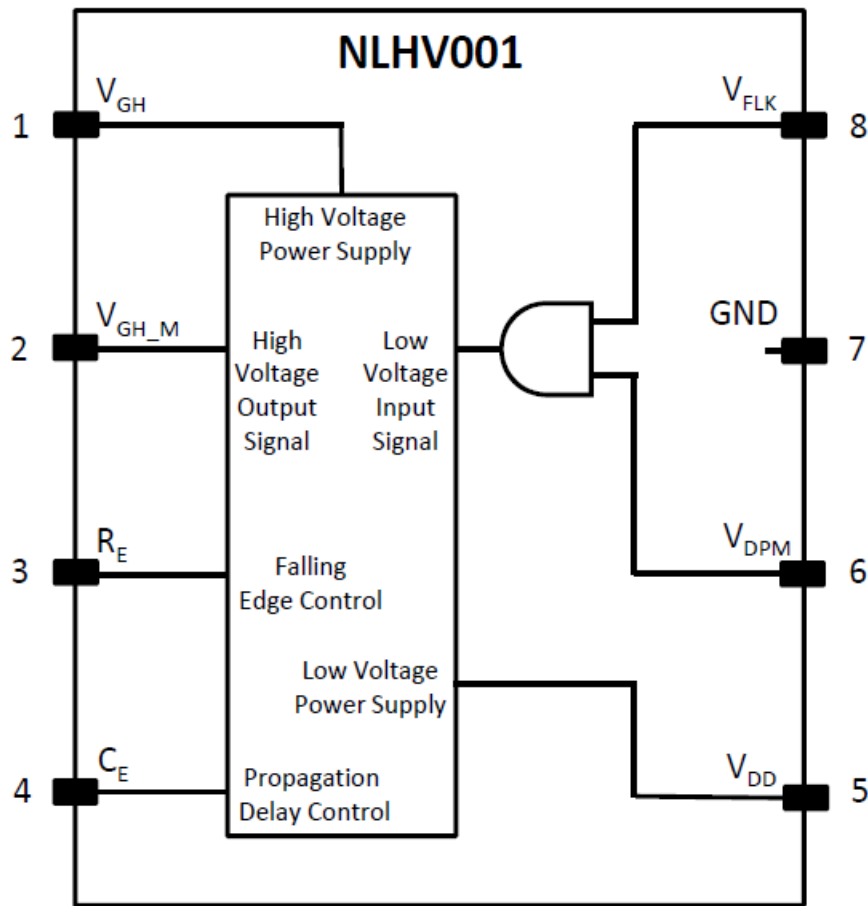


Figure 2. Block Diagram

## ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Condition	Value	Unit
$V_{GH}$	DC Supply Voltage		-0.5 to +40	V
$V_{DD}$	DC Supply Voltage		-0.5 to +40	V
$V_{FLK}$	Input Voltage $V_{FLK}$		-0.5 to +40	V
$V_{DPM}$	Input Voltage $V_{DPM}$		-0.5 to +40	V
$V_{GH} - V_{CE}$	Differential Voltage Between $V_{GH}$ and $V_{CE}$ Pins (Note 1)		9.5	V
$I_{IK}$	DC Input Diode Current		50	mA
$I_{OK}$	DC Output Diode Current		50	mA
$I_O$	DC Output Current		50	mA
$I_{GH}$	DC Supply Current Per Supply Pin		50	mA
$P_D$	Power Dissipation		200	mW
$T_J$	Junction Temperature		95	°C
$T_{STG}$	Storage Temperature		-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. A differential voltage between the  $V_{GH}$  and  $V_{CE}$  pins ( $V_{GH} - V_{CE}$ ) occurs during the power-up and power-down procedure. The voltages on the  $V_{GH}$  and  $C_E$  pins are equal at steady-state conditions after power-up.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
$V_{GH}$	DC Supply Voltage (Note 2)	$V_{GH} - V_{DD} \geq 8.5 \text{ V}$	15	–	38	V
$V_{DD}$	DC Supply Voltage	$V_{DD} \leq V_{GH} - 8.5 \text{ V}$	0	–	25	V
$V_{FLK}$	Input Voltage $V_{FLK}$	$V_{GH\_M} = V_{GH} - 1.2 \text{ V}$	1.5	–	$V_{GH}$	V
$V_{DPM}$	Input Voltage $V_{DPM}$	$V_{GH\_M} = V_{DD} + 1.5 \text{ V}$	0	–	$V_{GH}$	V
$T_A$	Operating Temperature Range		-40	–	85	V
$V_{GH} - V_{CE}$	Differential Voltage Between $V_{GH}$ and $V_{CE}$ Pins (Note 3)		–	–	5.5	V
$\Delta t / \Delta V_{GH}$	Safe $V_{GH}$ Power-Up Slew Rate (Note 4)	$C_E = 5 \text{ pF}$	–	0.2	–	$\mu\text{s} / \text{V}$
		$C_E = 10 \text{ pF}$		0.4		
		$C_E = 50 \text{ pF}$		0.6		
		$C_E = 150 \text{ pF}$		0.7		
		$C_E = 220 \text{ pF}$		0.8		
		$C_E = 500 \text{ pF}$		1.2		
		$C_E = 1000 \text{ pF}$		2.2		

2. Maximum recommended  $V_{GH}$  supply voltage guaranteed by design.
3. A differential voltage between the  $V_{GH}$  and  $V_{CE}$  pins ( $V_{GH} - V_{CE}$ ) occurs during the power-up and power-down procedure. The voltages on the  $V_{GH}$  and  $C_E$  pins are equal at steady-state conditions after power-up.
4. It is recommended that a ceramic or tantalum decoupling capacitor of 0.1 to 1  $\mu\text{F}$  is used on the  $V_{GH}$  power supply voltage. The capacitor should be placed adjacent to the NLHV001 and connected between  $V_{GH}$  and Ground.

# NLHV001

**ELECTRICAL CHARACTERISTICS** ( $V_{GH} = 20\text{ V}$ ,  $V_{DD} = 10\text{ V}$ ,  $V_{DPM} = 2.2\text{ V}$ ,  $V_{FLK} = 2.2\text{ V}$ ,  $V_{GH} - V_{DD} \geq 8.5\text{ V}$ ,  $T_a = 25\text{ }^\circ\text{C}$ , unless otherwise noted.)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
$V_{FLK\_H}$	FLK High Voltage	$V_{GH\_M} = V_{GH} - 1.6$	1.5	–	$V_{GH}$	V
$V_{FLK\_L}$	FLK Low Voltage	$V_{GH\_M} = V_{DD} + 1.5$	0	–	0.5	V
$V_{DPM\_H}$	DPM High Voltage	$V_{FLK} = 0\text{ V}$ , $V_{GH\_M} = V_{DD} - 0.2\text{ V}$	1.5	–	$V_{GH}$	V
$V_{DPM\_L}$	DPM Low Voltage	$V_{FLK} = 0\text{ V}$ , $V_{GH\_M} \leq 0.6\text{ V}$	0	–	0.5	V
$I_{DPM}$	DPM ON Current	$V_{FLK} = 3\text{ V}$ , $V_{GH\_M} = V_{GH}$	0.2	0.4	2	mA
$R_C$	$R_C$ (Resistor of $V_{DPM}$ pin)	$V_{GH} = 22\text{ V}$ , $R_C \approx (V_{GH} - 0.9) / I_{DPM}$ (Application Circuits 2 and 3)	10	45	100	k $\Omega$
$V_{GH\_M, H}$	Output High Voltage	$I_O = 10\text{ mA}$	$V_{GH} - 1.6$	$V_{GH} - 0.7$	–	V
$V_{GH\_M, R}$	Output Reset Voltage	$V_{DPM} = 0\text{ V}$ , $V_{FLK} = 3\text{ V}$	–	–	0.6	V
		$V_{DPM} = 0\text{ V}$ , $V_{FLK} = 0\text{ V}$				
$V_{GH\_M, L}$	Output Low Voltage	$V_{DPM} = 3\text{ V}$ , $V_{FLK} = 0\text{ V}$ , $I_O = -1\text{ mA}$	$V_{DD} - 0.2$	$V_{DD} + 0.3$	$V_{DD} + 0.8$	V
$I_{GH}$	Power Supply Input Current	$V_{GH} = 35\text{ V}$ , $V_{DD} = 15\text{ V}$ , $V_{FLK} = V_{DPM} = 3.3\text{ V}$ , $I_O = 0$	–	3.5	–	mA
$I_{DD}$	Reference Input Current	$V_{GH} = 35\text{ V}$ , $V_{DD} = 15\text{ V}$ , $V_{FLK} = 0\text{ V}$ , $V_{DPM} = 3.3\text{ V}$ , $I_O = 0$	–	40	–	$\mu\text{A}$

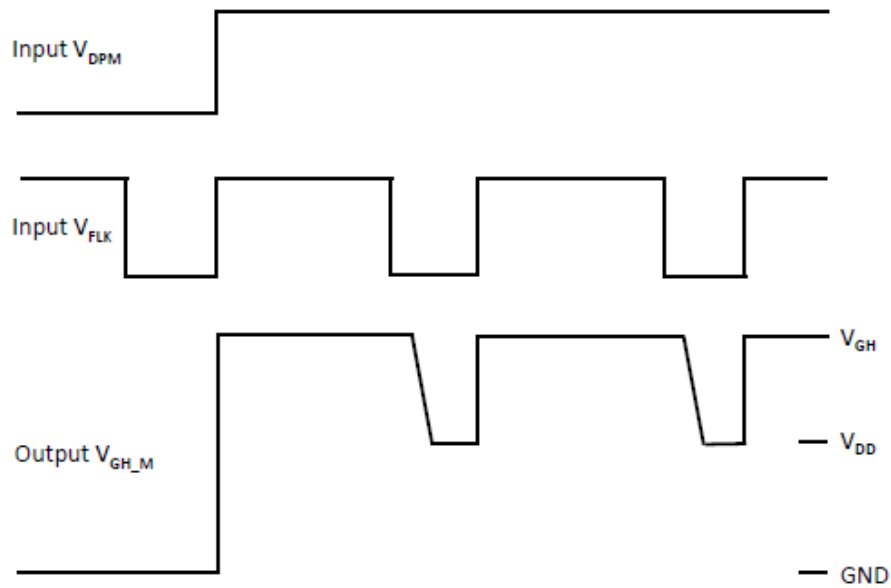


Figure 3. Input and Output Waveforms (Application Circuit #1)

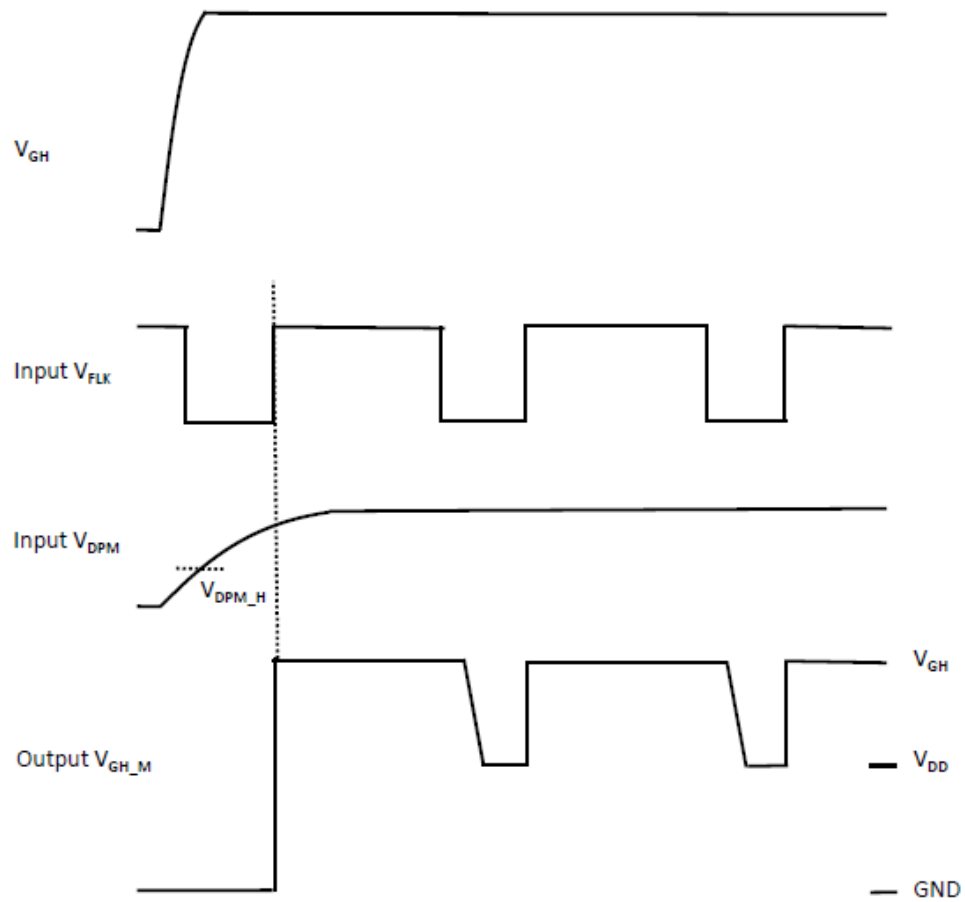


Figure 4. Input and Output Waveforms (Application Circuit #2)

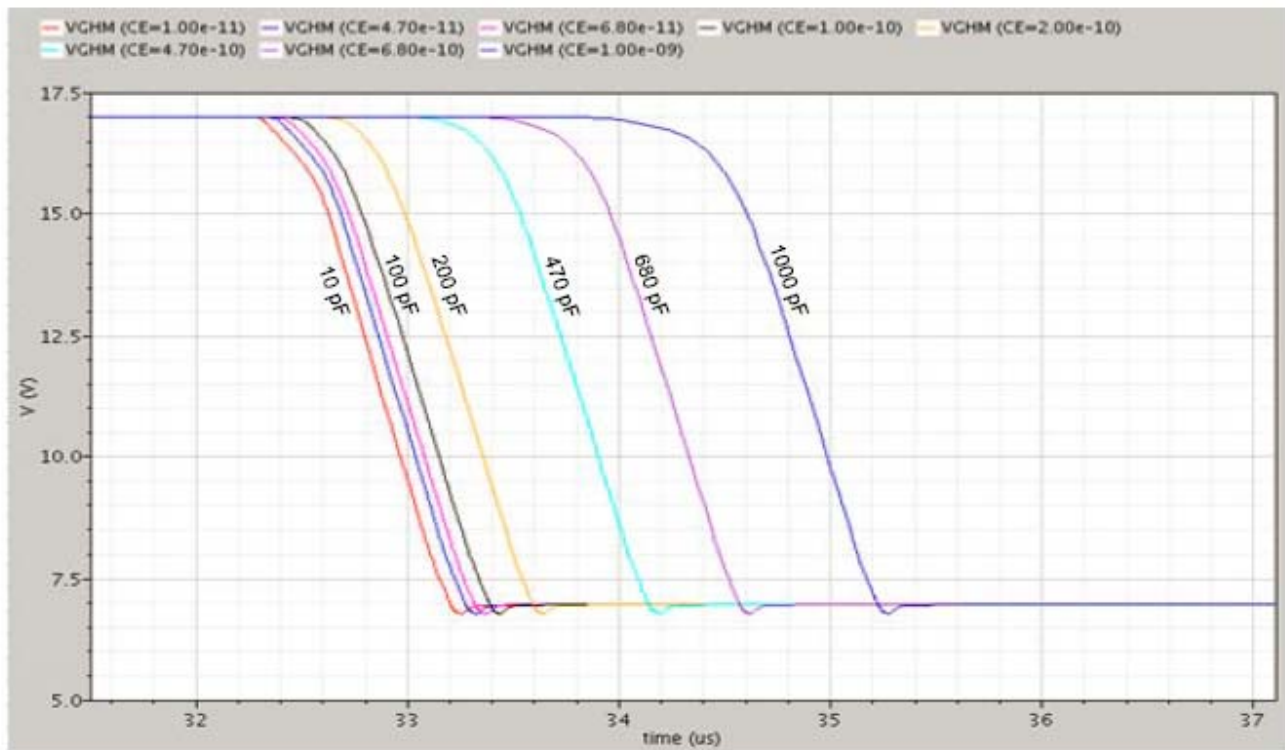


Figure 5.  $V_{GH\_M}$  Output Propagation Delay ( $t_{phl}$ ) is controlled by  $C_E$   
 (Application Circuit #1,  $V_{GH} = 18$  V,  $V_{DD} = 7$  V,  $R_E = 3.9$  k $\Omega$ ,  $R_L = 15$  k $\Omega$ ,  $C_L = 220$  pF,  $T_a = 25$  °C)

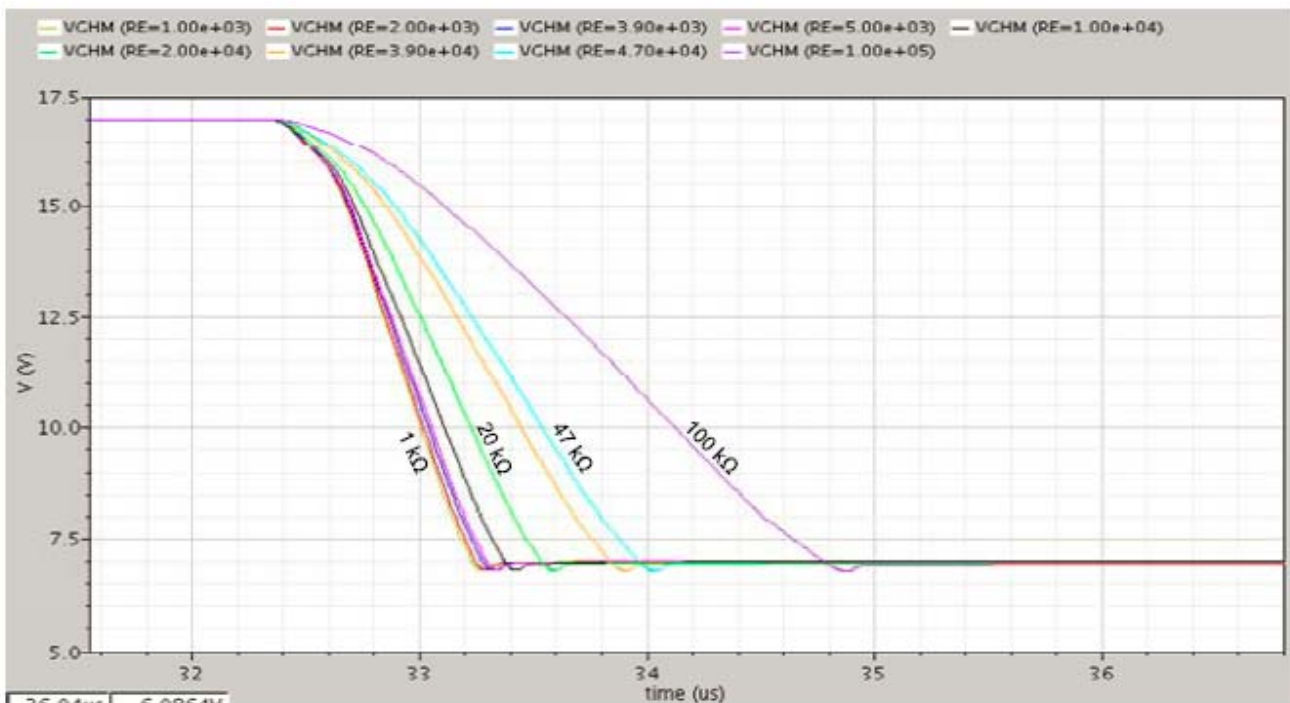


Figure 6.  $V_{GH\_M}$  Output Transition Falling Edge ( $t_{fall}$ ) is controlled by  $R_E$   
 (Application Circuit #1,  $V_{GH} = 18$  V,  $V_{DD} = 7$  V,  $C_E = 47$  pF,  $R_L = 15$  k $\Omega$ ,  $C_L = 220$  pF,  $T_a = 25$  °C)

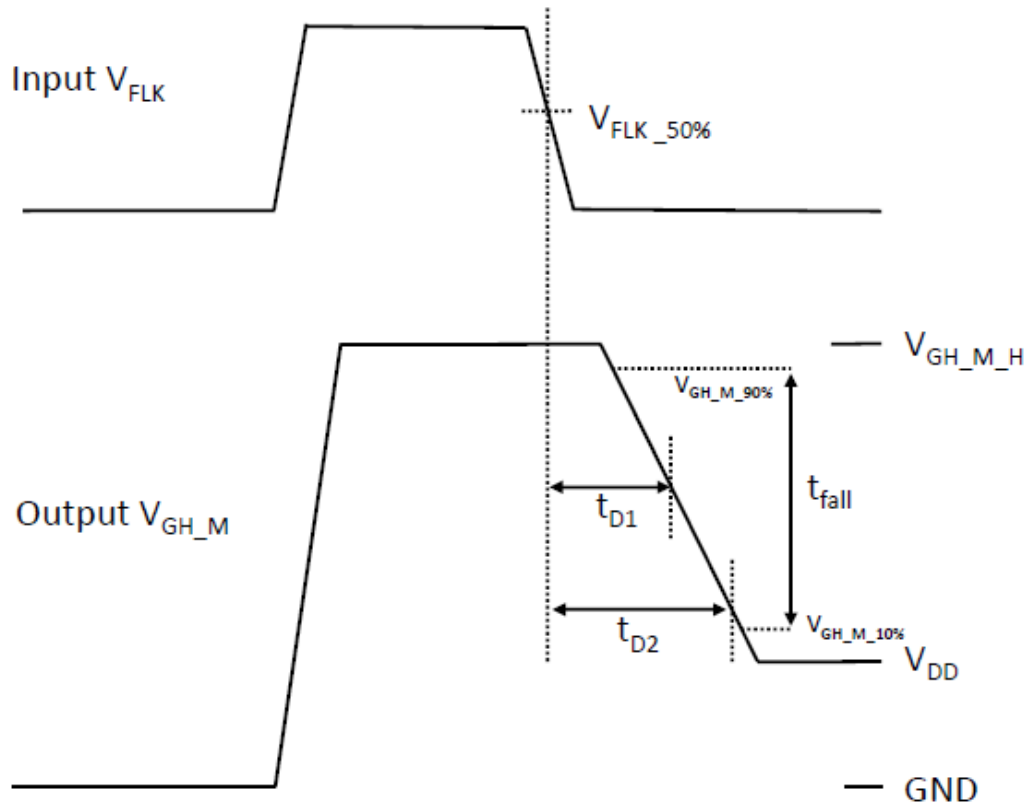


Figure 7.

**Definition of Delay Time**
 $t_{D1} = \text{Delay Time 1 (} t_{D_{50-50}} \text{)} = V_{FLK_{50\%}} \text{ to } [V_{DD} + ((V_{GH\_M\_H} - V_{DD}) \times 0.50)]$ 
 $t_{D2} = \text{Delay Time 2 (} t_{D_{50-15}} \text{)} = V_{FLK_{50\%}} \text{ to } [V_{DD} + ((V_{GH\_M\_H} - V_{DD}) \times 0.15)]$ 
 $t_{fall} = 90\text{-to-}10\% \text{ Fall Time} = [V_{DD} + ((V_{GH\_M\_H} - V_{DD}) \times 0.90)] - [V_{DD} + ((V_{GH\_M\_H} - V_{DD}) \times 0.10)]$ 
**DELAY TIME CHARACTERISTICS**(Application Circuit #1,  $V_{DPM} = 3 \text{ V}$ ,  $V_{FLK} = 3 \text{ V}$ ,  $R_E = 15 \text{ k}\Omega$ ,  $R_L = 15 \text{ k}\Omega$ ,  $C_L = 220 \text{ pF}$ ,  $T_A = 25^\circ\text{C}$ )

Parameter	Test Condition	Typ	Unit
Delay Time 2 ( $t_{D_{50-15}}$ )	$V_{GH} = 17 \text{ V}$ , $V_{DD} = 6.7 \text{ V}$ , $C_E = 100 \text{ pF}$	2.4	$\mu\text{s}$
	$V_{GH} = 17 \text{ V}$ , $V_{DD} = 6.7 \text{ V}$ , $C_E = 240 \text{ pF}$	2.8	$\mu\text{s}$
	$V_{GH} = 22.4 \text{ V}$ , $V_{DD} = 10 \text{ V}$ , $C_E = 91 \text{ pF}$	2.3	$\mu\text{s}$
	$V_{GH} = 22 \text{ V}$ , $V_{DD} = 10 \text{ V}$ , $C_E = 220 \text{ pF}$	2.8	$\mu\text{s}$
	$V_{GH} = 25.4 \text{ V}$ , $V_{DD} = 15.4 \text{ V}$ , $C_E = 56 \text{ pF}$	2.4	$\mu\text{s}$
	$V_{GH} = 25.4 \text{ V}$ , $V_{DD} = 15.4 \text{ V}$ , $C_E = 130 \text{ pF}$	2.5	$\mu\text{s}$



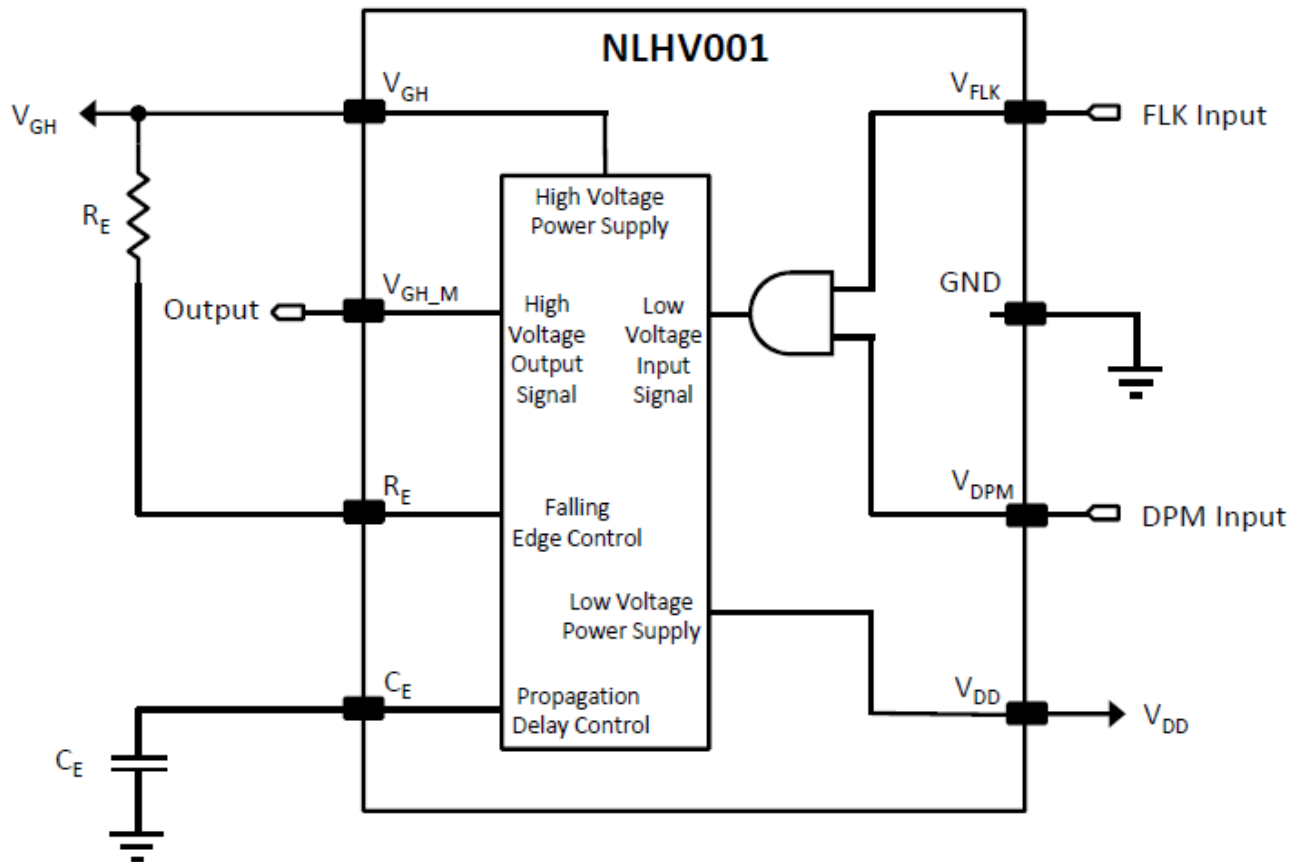


Figure 8. Application #1 Circuit Schematic

## Notes:

1.  $V_{DPM}$  can rise only after  $V_{GH}$  is valid.

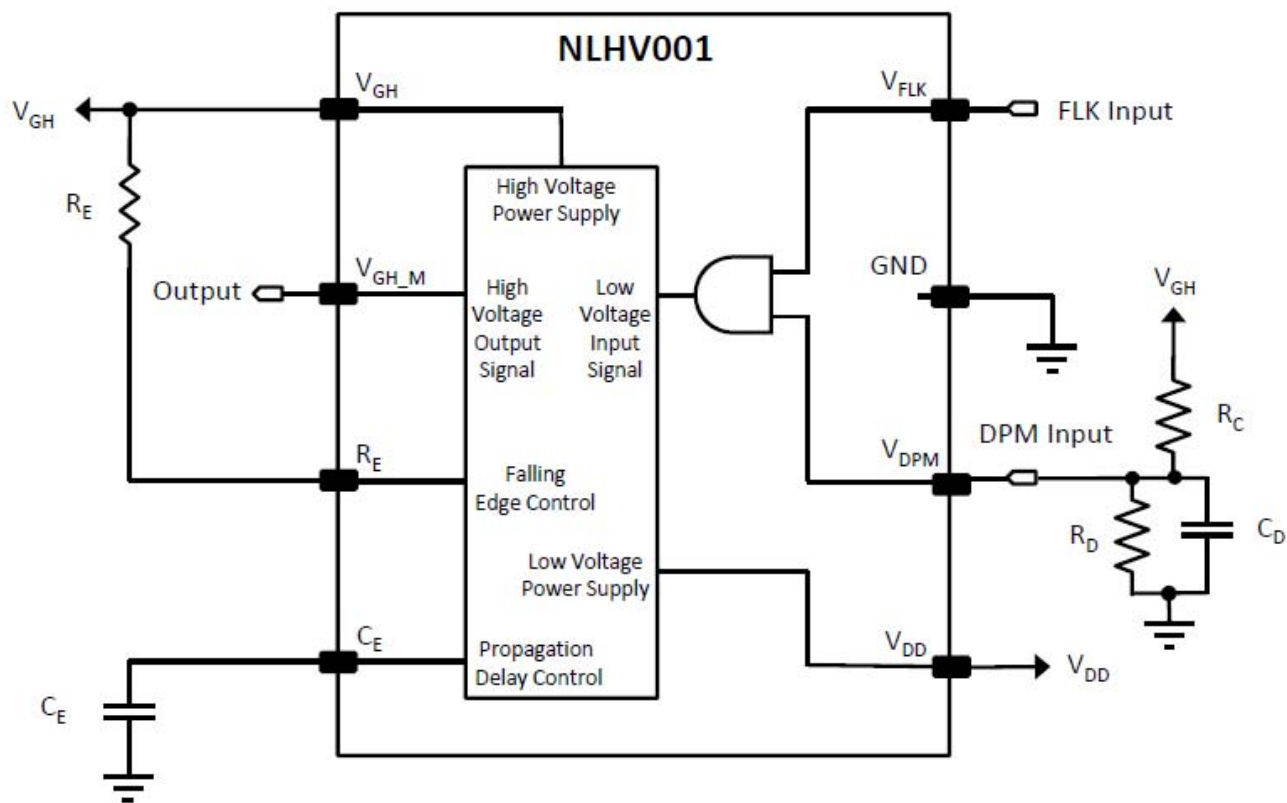


Figure 9. Application #2 Circuit Schematic

Notes:

- 1.  $V_{DPM}$  is produced by a Low Pass Filter (LPF) on  $V_{GH}$  pin with  $R_C$  and  $C_D$ .
- 2.  $R_D$  is a  $V_{DPM}$  pull-down resistor.

APPLICATION 2:  $V_{GH\_M}$  SIGNAL DELAY TIME CHARACTERISTICS

$V_{GH}$ (V)	$V_{DD}$ (V)	$C_D$ ( $\mu$ F)	$R_D$ (k $\Omega$ )	$R_C$ (k $\Omega$ )	$V_{GH\_M}$ ON Delay Time (when $V_{GH}$ ON) $t_{on}$ (ms)	$V_{DPM}$ Pin Discharge Time (when $V_{GH}$ OFF) $t_{off}$ (ms)
22	12	1	15	50	17.9	3.4
		1	1.5	20	5.5	1.4
		1	0.620	10	1.7	0.74

APPLICATION 2: FUNCTION DESCRIPTION

Name	Comment	Function
$R_C$	$R_C$ and $C_D$ determines the time when the $V_{DPM}$ pin is charged.	$t_{on}$ = Time when $V_{GH\_M}$ is high $t_{off}$ = Time when $V_{DPM}$ pin is fully discharged
$C_D$		
$R_D$	$R_D$ determines the time when the $V_{DPM}$ pin is discharged.	

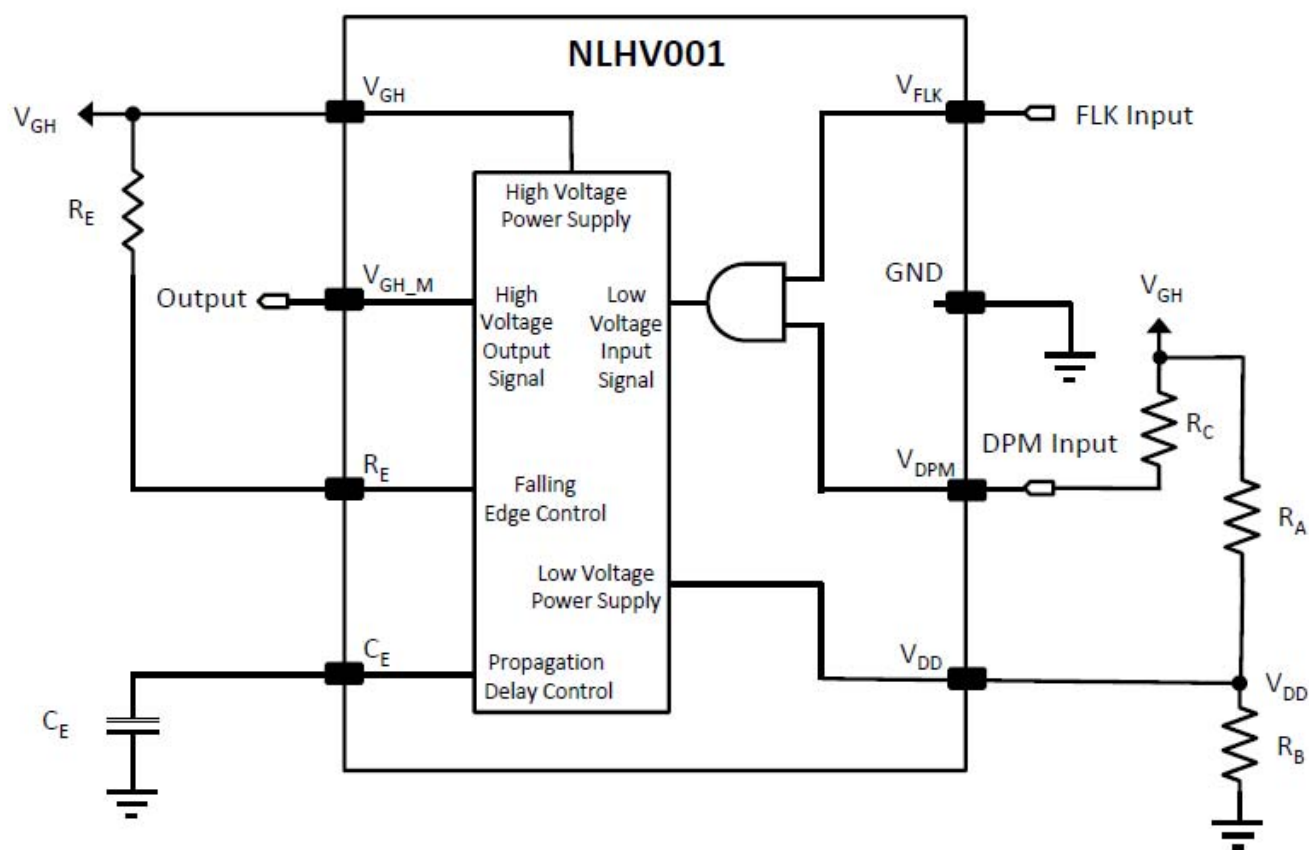


Figure 10. Application #3 Circuit Schematic

APPLICATION 3: FUNCTION DESCRIPTION

Name	Comment	Function
RA	RA and RB set the VDD voltage.	$V_{DD} = V_{GH} \times (R_B / (R_A + R_B))$
RB		
RC	RC determines the voltage that VDDM pin becomes high.	

Notes:

- 1. VDDM produced by external RC and internal R and C.
- 2. VDD created from external resistors RA and RB.
- 3. VGH should be higher than 18 V to meet VDDM\_H.
- 4. RA = 15 kΩ, RB = 10 kΩ, RC = 45 kΩ, RE = 15 kΩ, RL = 15 kΩ, CE = 220 pF, CL = 100 pF

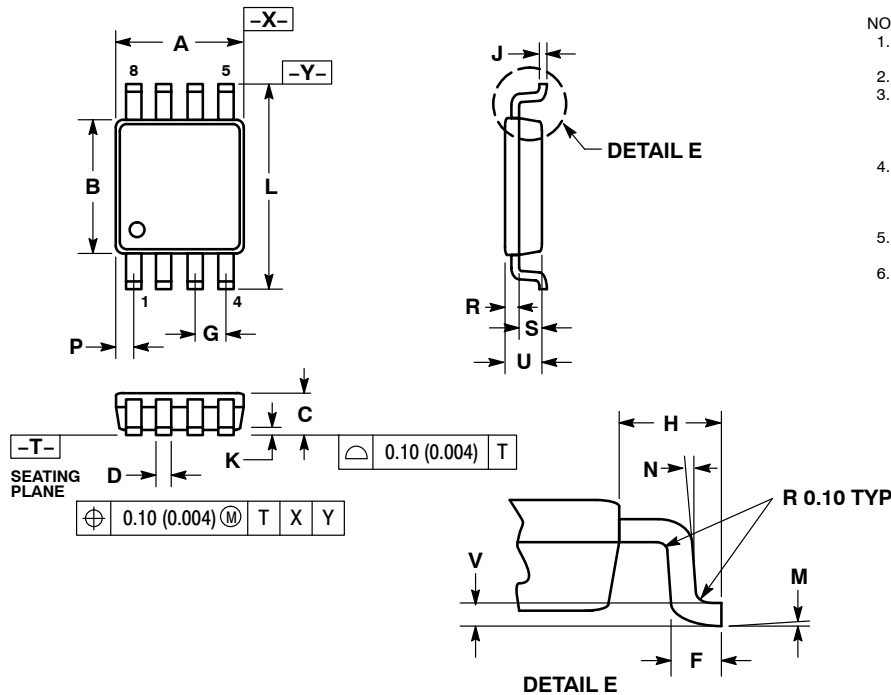
DEVICE ORDERING INFORMATION

Device Order Number	Package Type	Shipping†
NLHV001USG	US8 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## PACKAGE DIMENSIONS

US8  
CASE 493-02  
ISSUE B

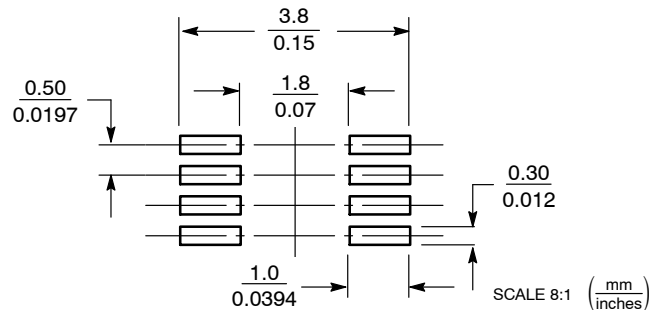


## NOTES:


1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH, PROTRUSION AND GATE BURR SHALL NOT EXCEED 0.140 MM (0.0055") PER SIDE.
4. DIMENSION "B" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTER-LEAD FLASH AND PROTRUSION SHALL NOT EXCEED 0.140 (0.0055") PER SIDE.
5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203 MM. (300-800").
6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED  $\pm 0.0508$  (0.0002").

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.90	2.10	0.075	0.083
B	2.20	2.40	0.087	0.094
C	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50 BSC		0.020 BSC	
H	0.40 REF		0.016 REF	
J	0.10	0.18	0.004	0.007
K	0.00	0.10	0.000	0.004
L	3.00	3.20	0.118	0.126
M	0°	6°	0°	6°
N	5°	10°	5°	10°
P	0.23	0.34	0.010	0.013
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
V	0.12 BSC		0.005 BSC	

## SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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